



Product Change Notification / JAON-20ILNW277

Date:

23-Oct-2020

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers, 32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4225 and 4225.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L QFN (9x9x0.9mm) and 28L QFN (6x6x0.9mm) packages at MTAI assembly site.

Affected CPNs:

[JAON-20ILNW277_Affected_CPN_10232020.pdf](#)

[JAON-20ILNW277_Affected_CPN_10232020.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L QFN (9x9x0.9mm) and 28L QFN (6x6x0.9mm) packages at MTAI assembly site.

Pre Change:

Assembled at MTAI using gold (Au) bond wire

Post Change: Assembled at MTAI using coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

| | Pre Change | Post Change |
|----------------------------------|--|--|
| Assembly Site | Microchip Technology Thailand (HQ) - (MTAI) | Microchip Technology Thailand (HQ) - (MTAI) |
| Wire material | Au | CuPdAu |
| Die attach material | 3280 | 3280 |
| Molding compound material | G700LTD | G700LTD |
| Lead frame material | C194 | C194 |

Impacts to Data Sheet: None.

Change Impact:None

Reason for Change:To improve manufacturability by qualifying coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:December 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

| | October 2020 | | | | | --> | December 2020 | | | | |
|--------------------------|--------------|--------|--------|--------|--------|-----|---------------|--------|--------|--------|--------|
| | 4 0 | 4 1 | 4 2 | 4 3 | 4 4 | | 4 9 | 5 0 | 5 1 | 5 2 | 5 3 |
| Initial PCN Issue Date | | | | X | | | | | | | |
| Qual Report Availability | | | | | | X | | | | | |
| Final PCN Issue Date | | | | | | X | | | | | |

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:October 23, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-20ILNW277_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

PIC24FJ1024GA606-E/MR
PIC24FJ128GA606-E/MR
PIC24FJ256GA606-E/MR
PIC24FJ512GA606-E/MR
PIC24FJ1024GB606-E/MR
PIC24FJ128GB606-E/MR
PIC24FJ256GB606-E/MR
PIC24FJ512GB606-E/MR
PIC24FJ1024GA606-I/MR
PIC24FJ128GA606-I/MR
PIC24FJ256GA606-I/MR
PIC24FJ512GA606-I/MR
PIC24FJ1024GB606-I/MR
PIC24FJ128GB606-I/MR
PIC24FJ256GB606-I/MR
PIC24FJ512GB606-I/MR
PIC24FJ1024GA606T-I/MR
PIC24FJ128GA606T-I/MR
PIC24FJ256GA606T-I/MR
PIC24FJ512GA606T-I/MR
PIC24FJ1024GB606T-I/MR
PIC24FJ128GB606T-I/MR
PIC24FJ256GB606T-I/MR
PIC24FJ512GB606T-I/MR
PIC24FJ128GL302-E/ML
PIC24FJ64GL302-E/ML
PIC24FJ128GL302-I/ML
PIC24FJ64GL302-I/ML
PIC24FJ128GL302T-I/ML
PIC24FJ64GL302T-I/ML
PIC24FJ128GL406-E/MR
PIC24FJ256GL406-E/MR
PIC24FJ512GL406-E/MR
PIC24FJ128GU406-E/MR
PIC24FJ256GU406-E/MR
PIC24FJ512GU406-E/MR
PIC24FJ128GL406-I/MR
PIC24FJ256GL406-I/MR
PIC24FJ512GL406-I/MR
PIC24FJ128GU406-I/MR
PIC24FJ256GU406-I/MR
PIC24FJ512GU406-I/MR
PIC24FJ128GL406T-I/MR
PIC24FJ256GL406T-I/MR
PIC24FJ512GL406T-I/MR
PIC24FJ128GU406T-I/MR

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PIC24FJ256GU4061-I/MR

PIC24FJ512GU406T-I/MR

PIC24FJ256GA702-E/ML

PIC24FJ128GA702-E/ML

PIC24FJ64GA702-E/ML

PIC24FJ256GA702-I/ML

PIC24FJ128GA702-I/ML

PIC24FJ64GA702-I/ML

PIC24FJ256GA702T-I/ML

PIC24FJ128GA702T-I/ML

PIC24FJ64GA702T-I/ML

PIC32MM0064GPM028-E/ML

PIC32MM0128GPM028-E/ML

PIC32MM0256GPM028-E/ML

PIC32MM0064GPM028-I/ML

PIC32MM0128GPM028-I/ML

PIC32MM0256GPM028-I/ML

PIC32MM0256GPM028T-I/ML026

PIC32MM0256GPM028T-I/ML028

PIC32MM0064GPM028T-I/ML

PIC32MM0128GPM028T-I/ML

PIC32MM0256GPM028T-I/ML

PIC32MM0016GPL028-E/ML

PIC32MM0032GPL028-E/ML

PIC32MM0064GPL028-E/ML

PIC32MM0016GPL028-I/ML

PIC32MM0032GPL028-I/ML

PIC32MM0064GPL028-I/ML

PIC32MM0016GPL028T-I/ML

PIC32MM0032GPL028T-I/ML

PIC32MM0064GPL028T-I/ML